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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

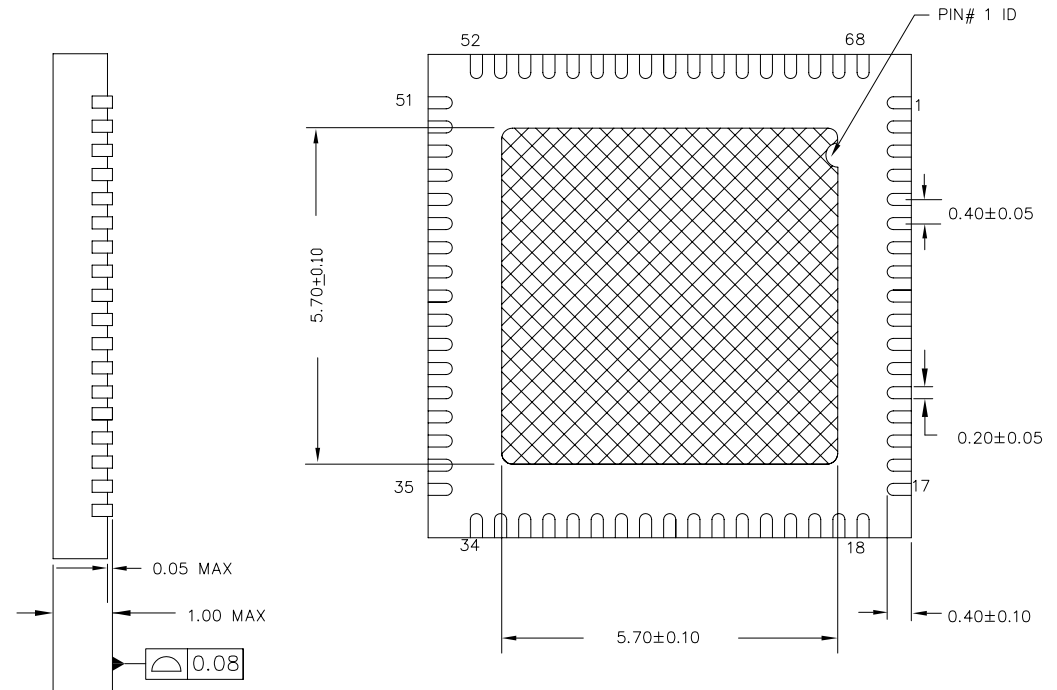
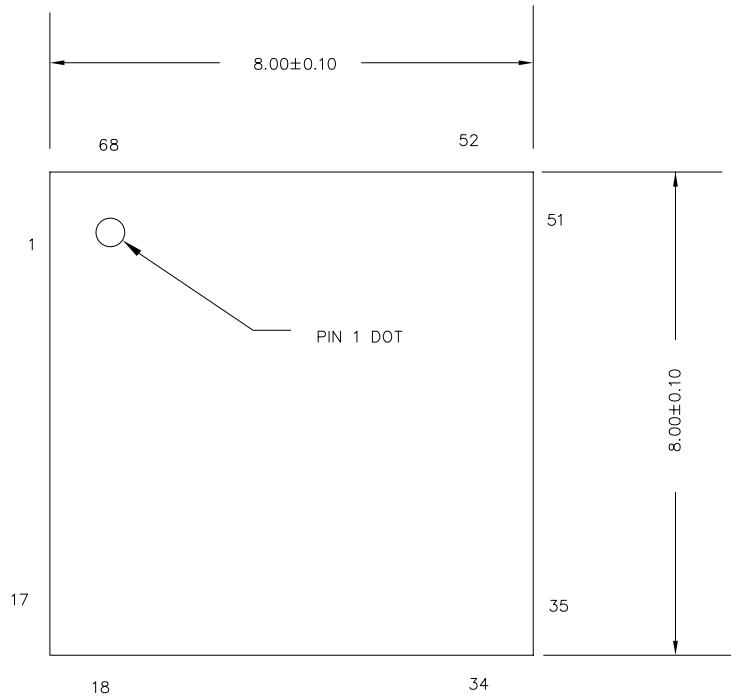
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	493148	NEW RELEASE	08/08/06	N/A
1	-	*A	2515796	UPDATED SPEC TITLE AND DIMENSION FORMAT	06/13/08	N/A
1	-	*B	2741531	CORRECTED LEAD WIDTH DIMENSION AND TOLERANCE. CORRECTED LEAD SPREAD DIMENSION AND CHANGED SPEC TITLE FROM 8X8X0.90 TO 8X8X1.0MM	07/29/09	N/A
1	-	*C	2811399	CHANGE TEMPLATE TO STANDARD FORMAT	11/20/09	QAD
1	-	*D	3328470	NO CHANGE. SUNSET REVIEW.	07/26/11	N/A
1	-	*E	3524505	FORMAT REVISION, PER MEMO MLA-770	7/10/12	MLA

TOP VIEW

SIDE VIEW

BOTTOM VIEW



NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO-220
3. PACKAGE WEIGHT: 17 ± 2mg
4. ALL DIMENSIONS ARE IN MILLIMETERS



TITLE PACKAGE OUTLINE, 68L QFN 8X8X1.0MM LT68
5.7X5.7 EPAD (SAWN TYPE)

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MATERIAL	SEE NOTES	DRAWN BY	MLA	DATE	7/10/12
FINISH	SEE NOTES	APPROVED BY	BSC	DATE	7/10/12

SIZE	PART NO.	DWG NO	REV
A	LT68	001-09618	*E
SCALED TO FIT			SHEET 1 OF 1